Protec GmbH
High-Rel Electronic Components

SPACE COMPONENTS NEWSLETTER December 2020

SEMICOA

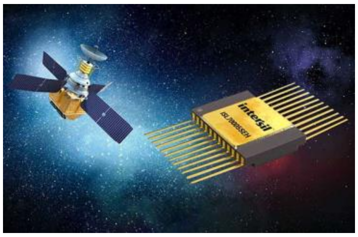
Semicoa is shipping record numbers of parts per month through increases in manpower and better efficiencies. In addition qualified more wafers for stock.

What this means is our lead times for high runners such as the 2N2222, 2N2907 and 2N3700 are now down to about 16 weeks, if not in stock (JANS to JANSR). We will continue to add other part numbers to this reduced 16 week lead time.

If there are part numbers you would like to see us add to this list, let us know.

RENESAS intersil

ISL70005SEH is radiation hardened dual output Point-of-Load (POL) regulator combining the high efficiency of a synchronous buck regulator with the low noise of a Low Dropout (LDO) regulator. They are suited for systems with 3.3V or 5V power buses and can support continuous output load currents of 3A for the buck regulator and ±1A for the LDO.

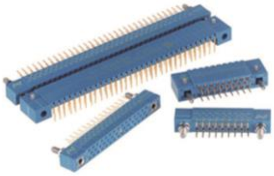


The buck regulator uses a voltage mode control architecture and switches at a adjustable frequency of 100kHz to 1MHz. Externally adjustable loop compensation allows for an optimum balance between stability and output dynamic performance. The internal synchronous power switches are optimized for high efficiency and excellent thermal performance.

The LDO is completely configurable independent of the switching regulator. It uses NMOS pass devices and separate chip bias voltage (L_VCC) to drive its gate, enabling the LDO to operate with a very low voltage at the L_VIN input. The LDO can sink and source up to 1A continuously, making it an ideal choice to power DDR memory.

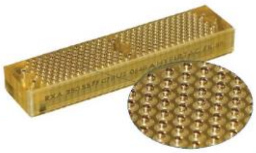
The ISL70005SEH is available in a 28 Ld ceramic dual flat-pack or die. It is specified to operate across a temperature range of TA = -55°C to +125°C.

smiths interconnect



KMC Series
ESA Qualified (ESCC 3401/039)
high density board to board and board to wire interconnect available in multiple configurations from 26 to 162 positions.

MHD/MDD/MDP Series
ESA Qualified (ESCC 3401/065)
high density board to board and board to wire interconnect available in up to 400 positions, with available insulators to accommodate coax and power contacts.



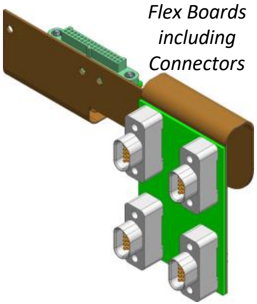
HyperStac Series
ESA Qualified (ESCC 3401/076)
a Z axis interconnection solution for mezzanine packaging designed for all types of micro-electronics applications requiring reliable and compact packaging solutions, interconnection of MCMs (Multi Chip Module) to PCBs, MCM to MCM, PCB stacking, etc.

RENESAS intersil

ISL73141SEH 14-Bit, 1-MSPS ADC delivers best in class dynamic and static performance, including signal-to-noise ratio, effective number of bits, integral non-linearity and differential non-linearity. The ADC fully resets after every sample, clearing any errors that result from a single event upset (SEU) due to heavy ion radiation during spaceflight.

Stay tuned more ADCs soon.

AirBorn



Flex Boards including Connectors

Beginning with the Apollo Missions, Voyager Missions, ISS, Shuttles, Hubble, Mars Rover and innumerable Earth-orbiting satellites.

From deep sea to deep space, our innovative interconnect, value add & box build solutions are chosen by leading companies in space exploration to operate their most critical systems, in the most hostile environments.

Micro-D Connectors and many other interconnect solutions